

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S2	80	438/117,122,125.ccls. and (bond adj wire) and encapsula\$6 and (heat adj (slug or sink or dissipat\$6 or spreader)) and @ad<="20040211"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/04 08:33
S3	100	257/706,707,720.ccls. and (bond adj wire) and encapsula\$6 and (heat adj (slug or sink or dissipat\$6 or spreader)) and @ad<="20040211"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/04 08:33
S5	7	"5972736".URPN.	USPAT	OR	ON	2004/11/04 09:30
S6	206	(438/109).CCLS.	USPAT; USOCR	OR	OFF	2004/10/08 14:13
S7	467	(438/118).CCLS.	USPAT; USOCR	OR	OFF	2001/02/14 13:31
S8	201	(438/108).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 14:38
S9	6	(("5863814") or ("6063647") or ("5904495") or ("5837562") or ("5783465") or ("4545840")).PN.	USPAT; USOCR	OR	OFF	2005/12/22 11:04
S10	510	(438/106).CCLS.	USPAT; USOCR	OR	OFF	2005/09/16 09:06
S11	223	(438/109).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 14:18
S12	266	(438/108).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 14:39
S13	116	(438/117).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 14:42
S14	401	(438/127).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 14:45
S15	523	(438/118).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 14:46
S16	372	(438/612).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 14:49
S17	341	(438/613).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 14:50
S18	347	(438/15).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 14:51
S19	194	(438/111).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 14:52
S20	181	(438/112).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 14:52
S21	330	(438/122).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 14:54

S22	94	(438/110).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 14:55
S23	5	(("4323914") or ("4034469") or ("5325265") or ("5923086") or ("5396403")).PN.	USPAT; USOCR	OR	OFF	2005/06/17 10:19
S24	350	(438/108).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/03/22 13:06
S25	604	(438/118).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/03/21 10:59
S26	285	(438/109).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/03/21 11:00
S27	127	(438/117).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/03/21 11:00
S28	482	(438/127).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/03/21 11:01
S29	604	(438/118).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/03/21 11:02
S30	396	(438/613).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/03/21 11:03
S31	392	(438/15).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/03/21 11:04
S32	219	(438/111).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/03/21 11:04
S33	221	(438/112).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/03/21 11:04
S34	1576	(438/106).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/03/21 11:06

S35	633	(438/106).CCLS.	USPAT; USOCR	OR	OFF	2002/03/22 12:57
S36	350	(438/108).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/03/22 13:06
S37	1567	(438/612).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/03/22 13:43
S38	1419	438/109,118,108,106,117,127, 612,613,111,122,110.ccls. and (heat adj (slug or sink or dissipat\$6))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/08 14:21
S39	182	438/109,118,108,106,117,127, 612,613,111,122,110.ccls. and encapsula\$6 and (bond adj wire) and (heat adj (slug or sink or dissipat\$6))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/28 13:52
S40	699	"257"/\$.ccls. and encapsula\$6 and (bond adj wire) and (heat adj (slug or sink or dissipat\$6))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/28 13:53
S41	182	438/109,118,108,106,117,127, 612,613,111,122,110.ccls. and encapsula\$6 and (bond adj wire) and (heat adj (slug or sink or dissipat\$6))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/28 13:53
S42	242	"438"/\$.ccls. and encapsula\$6 and (bond adj wire) and (heat adj (slug or sink or dissipat\$6))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/22 10:42
S43	251	"438"/\$.ccls. and encapsula\$6 and (bond adj wire) and (heat adj (slug or sink or dissipat\$6 or spreader))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 13:39
S44	722	"257"/\$.ccls. and encapsula\$6 and (bond adj wire) and (heat adj (slug or sink or dissipat\$6 or spreader))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 14:14
S45	249	"438"/\$.ccls. and encapsula\$6 and (bond adj wire) and (heat adj (slug or sink or dissipat\$6 or spreader)) and @ad<="20040211"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 14:15

S46	748	semiconductor and encapsula\$6 and (bond adj wire) and (heat adj (slug or sink or dissipat\$6 or spreader)) and @ad<="20040211"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/01 14:15
S47	714	"257"/\$.ccls. and encapsula\$6 and (bond adj wire) and (heat adj (slug or sink or dissipat\$6 or spreader)) and @ad<="20040211"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/02 08:47
S48	1091	(438/123).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/03 12:39
S49	812	(438/125).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/03 14:51
S50	210	(438/117).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/03 12:39
S51	506	(438/122).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/11/03 14:47
S52	1194	(257/706).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/03 14:51
S53	812	(438/125).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/03 14:51
S54	797	(257/707).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/03 14:52

S55	680	(257/720).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/03 14:52
S56	1553	438/117;122,125.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/04 08:32
S57	2247	257/706,707,720.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/04 08:32
S58	230	(257/703).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 13:52
S59	239	(257/703).CCLS.	USPAT; USOCR	OR	OFF	2001/08/03 13:52
S60	569	(257/703).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2002/03/22 13:43
S61	1	("6650044").PN.	USPAT; USOCR	OR	OFF	2004/10/12 10:35
S66	0	(2001/0017392).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/02 08:54
S67	2	("20010017392").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/02 08:54
S68	2	("20030232467").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/02 10:39
S69	2	("20030122186").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/02 13:01



S70	1589	semiconductor with (flat adj package)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 11:49
S71	1036	semiconductor with (quad adj flat adj package)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/02 13:25
S72	0	semiconductor with (quad adj flat adj package) with (liquid adj resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/02 13:25
S73	0	semiconductor with (flat adj package) with (liquid adj resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/02 13:25
S74	20	(semiconductor with (quad adj flat adj package)) and (liquid adj resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/02 13:27
S75	22	(semiconductor with (flat adj package)) and (liquid adj resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/02 13:27
S76	2	("20020164869").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/03 08:01
S77	951	(257/777).CCLS.	USPAT; USOCR	OR	OFF	2004/11/03 08:01
S78	945	257/777.ccls. and @ad<="20040326"	USPAT	OR	ON	2004/11/03 08:12
S79	41	257/777.ccls. and (chamfer\$6 or bevel\$5 or obliq\$6)	USPAT	OR	ON	2004/11/03 13:10
S80	4	(gate adj structure) with (inter-layer) with ((chemical adj mechanical adj polish\$5) or ("CMP"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/03 13:11
S81	3	((("5970381") or ("6689473")) or ("20030171239")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/11/03 12:46

S82	1	("6475896").PN.	USPAT; USOCR	OR	OFF	2004/11/03 14:03
S83	1	("6730589").PN.	USPAT; USOCR	OR	OFF	2005/06/17 09:48
S85	1	("6737320").PN.	USPAT; USOCR	OR	OFF	2004/11/03 14:29
S89	506	(438/122).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/11/03 14:47
S90	506	(438/122).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/11/03 14:47
S91	1058	(257/722).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/03 14:50
S92	16	(semiconductor with (flat adj package)) and (bond adj wire) and (heat adj (slug or sink or dissipat\$6 or spreader)) and @ad<="20040211"	USPAT	OR	ON	2005/06/20 12:21
S95	3170	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/16 09:07
S96	1371	(438/108).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/16 09:07
S97	43	(semiconductor and encapsula\$6 and (bond adj wire) and (heat adj (slug or sink or dissipat\$6))).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/22 10:55
S98	12	(semiconductor and encapsula\$6 and (bond adj wire) and (heat adj (slug or sink or dissipat\$6))).clm.	US-PGPUB	OR	ON	2005/12/22 10:43
S99	7	(("4509096") or ("4876588") or ("5438478") or ("6552264") or ("5294750") or ("5367193") or ("5644163")).PN.	USPAT; USOCR	OR	OFF	2005/12/22 12:52